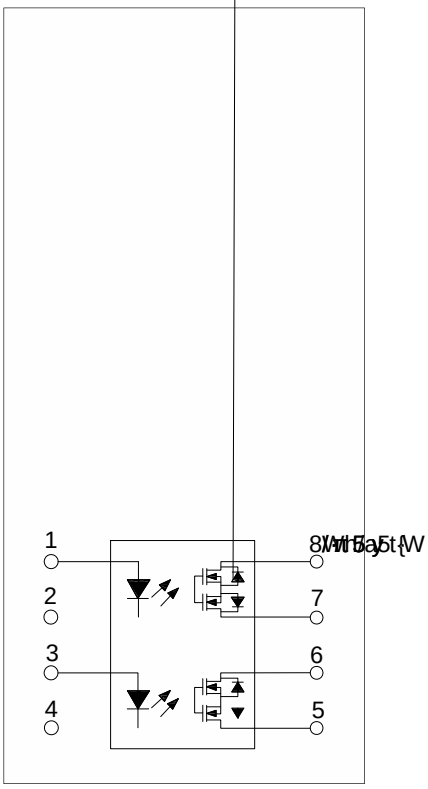
JOCMDXXC-D8P/S Series

Rev.A.1.0

DESCRIPTION:

The products are 8-pin optical relays. The device consists of an AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit in a plastic DIP8 package with different lead forming options. The detector consists of a high-speed photovoltaic diode array and driver circuitry. The products are widely used in isolation in high-speed inspection machines, telephones equipment and computers.



MAIN FEATURES

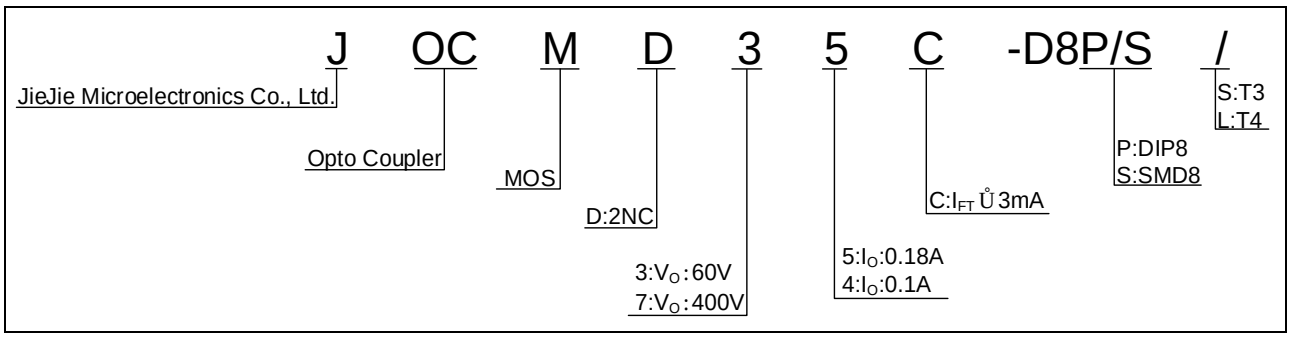
High isolation 5000 Vrms
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter			Symbol	Value	Unit
Input	Forward Current		I_F	50	mA
	Peak Forward Current		I_{FP}	1[1]	A
	Reverse Voltage		V_R	6	V
	Input Power Dissipation		P_D	75	mW
Output	Load Voltage	JOCMD35C	V_L	60	V
		JOCMD74C		400	
	Continuous load current	JOCMD35C	I_L	0.18	A
		JOCMD74C		0.1	
	Output Power Dissipation		P_O	600	mW
Total Power Dissipation			P_{tot}	675	mW
Isolation Voltage			V_{iso}	5000[2]	Vrms
Operating Temperature			T_{opr}	-40~110	℃
Junction Temperature			T_j	125	℃
Storage Temperature			T_{stg}	-40~125	℃

Soldering Temperature	T

ORDERING INFORMATION



Packing Quantity			
Option	**Quantity**	**Quantity – Inner box**	**Quantity –Outer box**
DIP	50 Units/Tube	40 Tubes/Inner box	5 Inner box/Outer box =10k Units
SMD	1200 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box =12k Units

MARKING

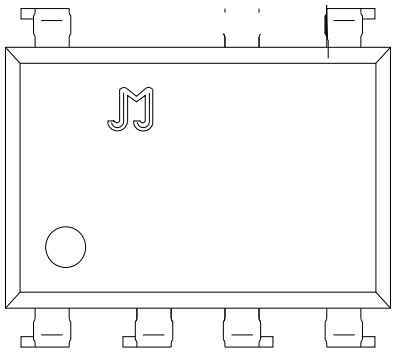


FIG.2: Output Current vs. Output Voltage

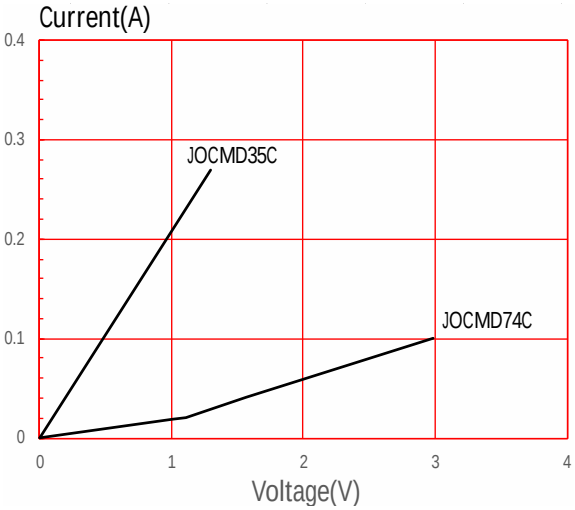


FIG.4: Load Current vs. Ambient Temperature

FIG.7: Turn On Time vs. Ambient Temperature

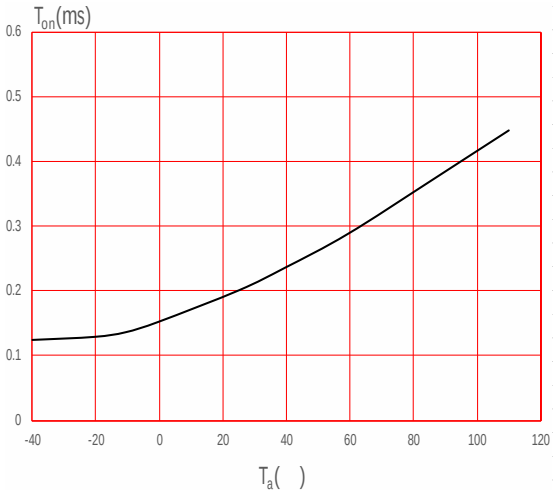


FIG.8: Turn Off Time vs. Ambient Temperature

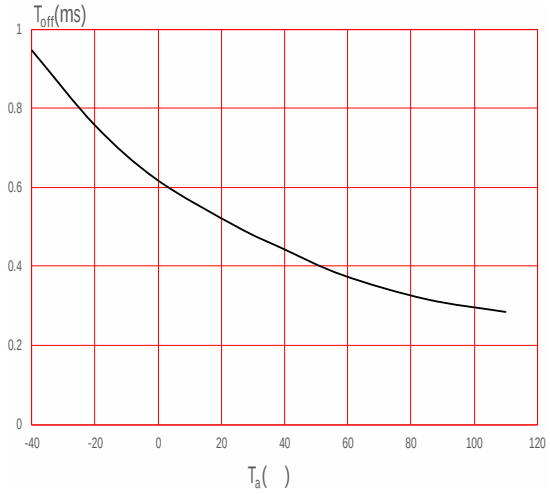
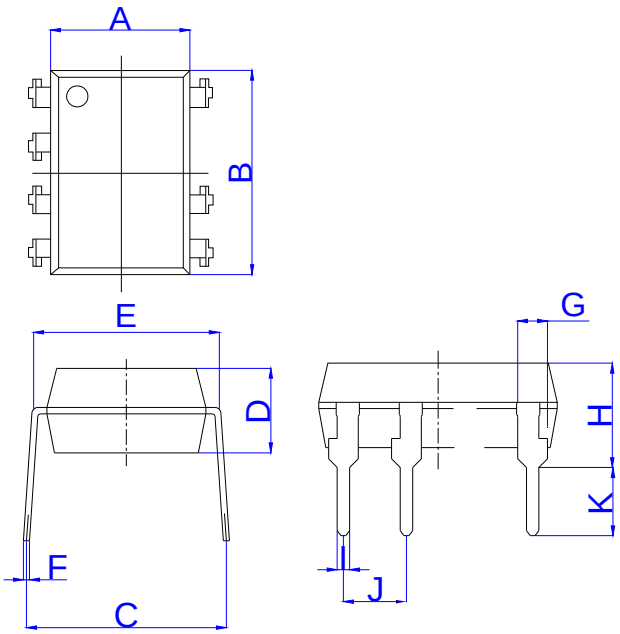


FIG.9: Turn On Time vs. LED Forward Current

FIG.10: Turn Off Time vs. LED Forward Current

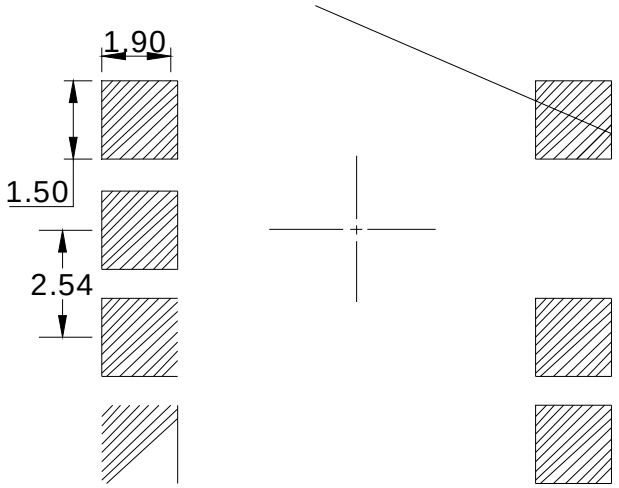
Package Dimension (Unit: mm)

Standard DIP Type:



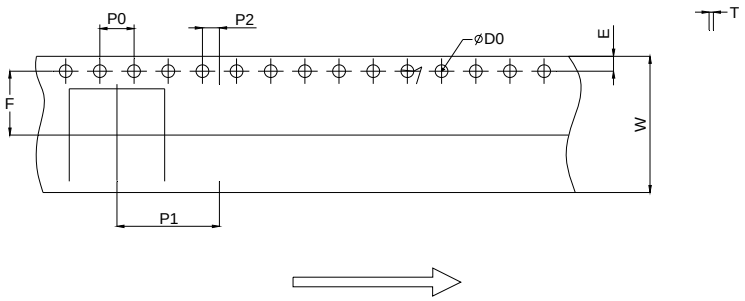
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J						

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



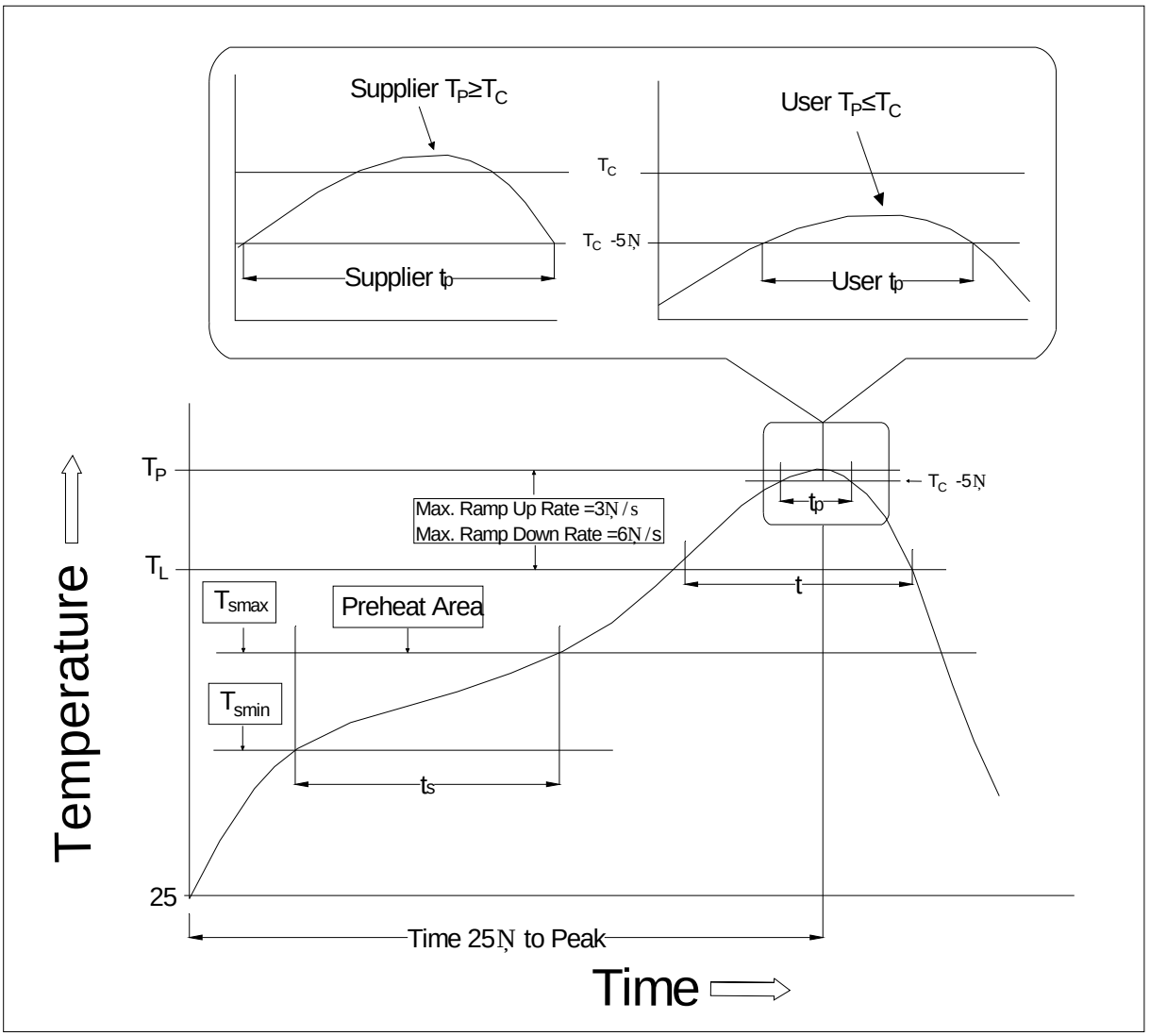
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S



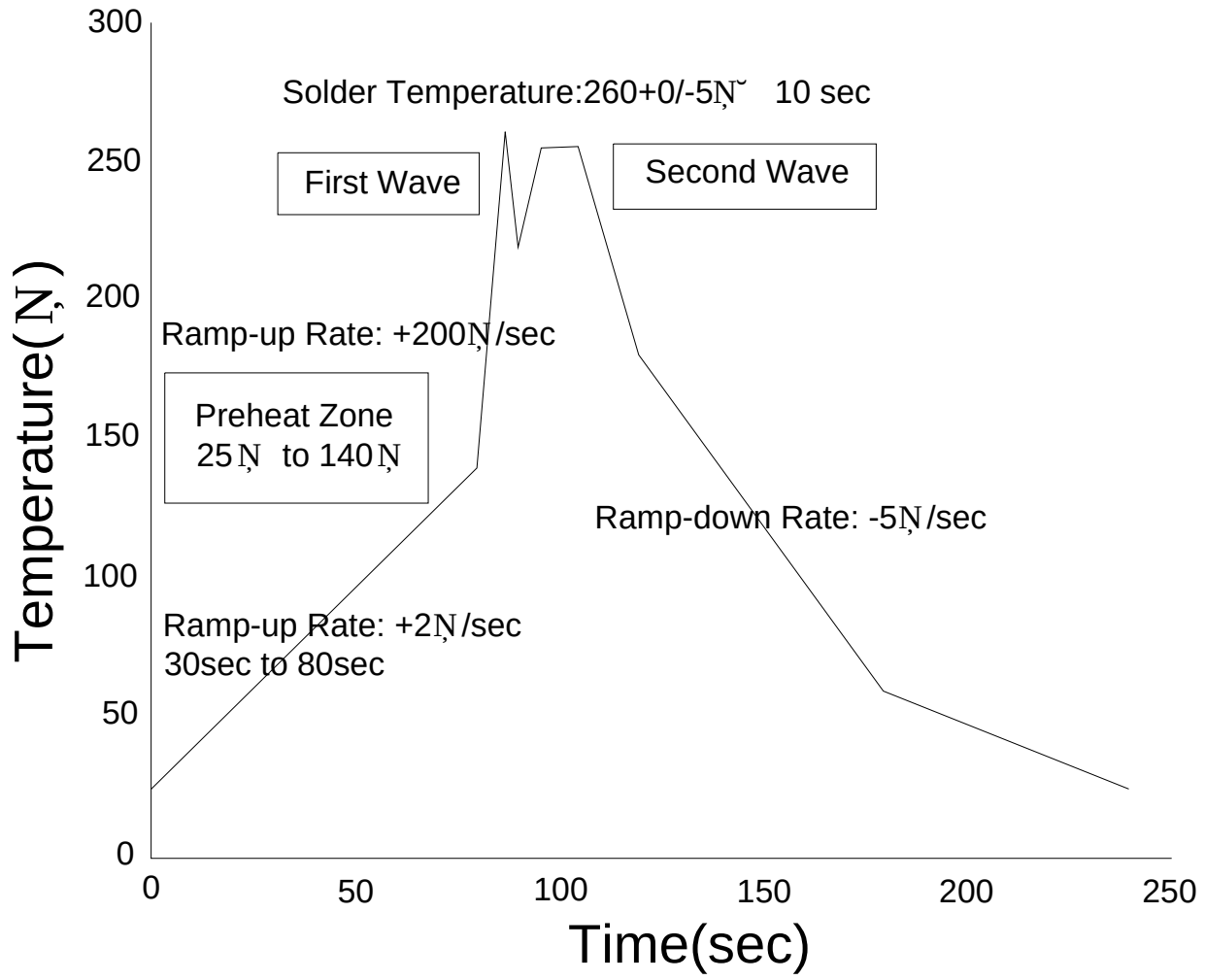
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100℃	150℃
Temperature Max. (Tsmax)	150℃	200℃
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3℃/second max.	3℃/second max.
Liquidus Temperature (TL)	183℃	217℃
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235℃+0℃/-5℃	260℃+0℃/-5℃
Time (tP) within 5℃ of 260℃	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6℃/second	3-6℃/second

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 ¤ 5Ņ
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.

is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.

Copyright © 2026 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.